

Features

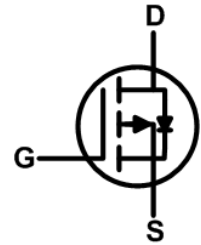
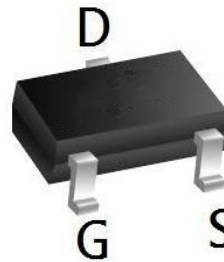
- Advanced Trench MOS Technology
- Green Device Available

Product Summary

BVDSS	RDSON	ID
-150V	2.4Ω	-0.55A

Applications

- Load Switch.
- Power Management.
- LED Backlighting.
- Networking Application.

SOT23 Pin Configuration

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-150	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_{D@T_A=25^{\circ}C}$	Continuous Drain Current, $-V_{GS}$ @ -10V ¹	-0.55	A
$I_{D@T_A=70^{\circ}C}$	Continuous Drain Current, $-V_{GS}$ @ -10V ¹	-0.44	A
I_{DM}	Pulsed Drain Current ²	-3.3	A
EAS	Single Pulse Avalanche Energy ³	1.25	mJ
I_{AS}	Avalanche Current	-5	A
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ⁴	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	90	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	35	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-150	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=-10V, I_D=-0.42A$	---	2.0	2.4	Ω
		$V_{GS}=-7V, I_D=-0.2A$	---	2.1	3.0	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-3.5	-4.8	-5.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-120V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{DS}=-120V, V_{GS}=0V, T_J=85^\circ\text{C}$	---	---	-30	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
Q_g	Total Gate Charge	$V_{DS}=-75V, V_{GS}=-10V, I_D=-0.4A$	---	3.75	---	nC
Q_{gs}	Gate-Source Charge		---	1.54	---	
Q_{gd}	Gate-Drain Charge		---	1.07	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-75V, V_{GS}=-10V, R_G=1\Omega, I_D=-0.42A$	---	8.3	---	ns
T_r	Rise Time		---	10.5	---	
$T_{d(off)}$	Turn-Off Delay Time		---	15	---	
T_f	Fall Time		---	19	---	
C_{iss}	Input Capacitance	$V_{DS}=-75V, V_{GS}=0V, f=1\text{MHz}$	---	238	---	pF
C_{oss}	Output Capacitance		---	17	---	
C_{rss}	Reverse Transfer Capacitance		---	7	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current	---	---	-1.8	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=-0.42A, T_J=25^\circ\text{C}$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	$I_F=-1A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	37.8	---	nS
Q_{rr}	Reverse Recovery Charge		---	60.7	---	nC

Note :

1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.

2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

3.The EAS data shows Max. rating . The test condition is $V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-5A$

4.The power dissipation is limited by 150°C junction temperature

5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation

Typical Characteristics

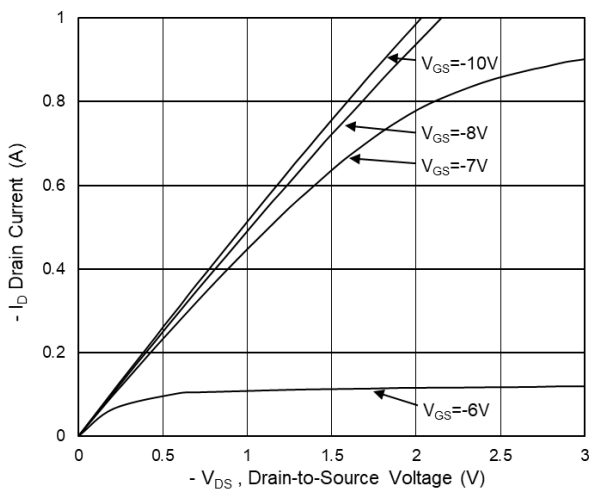


Fig.1 Typical Output Characteristics

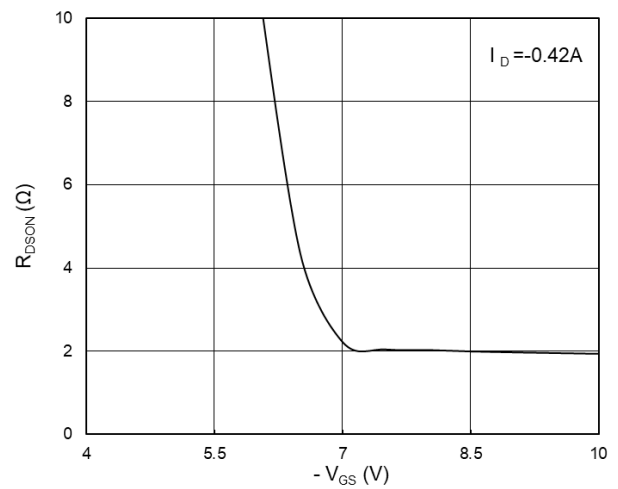


Fig.2 On-Resistance vs G-S Voltage

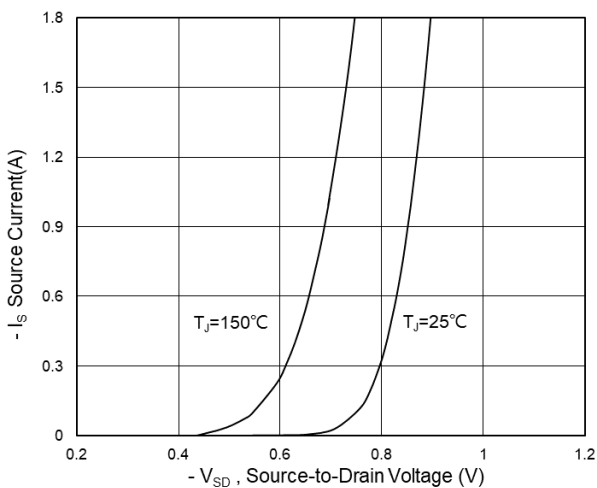


Fig.3 Source Drain Forward Characteristics

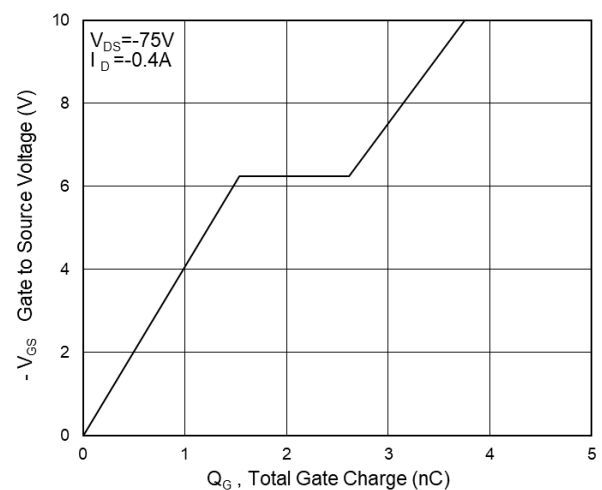


Fig.4 Gate-Charge Characteristics

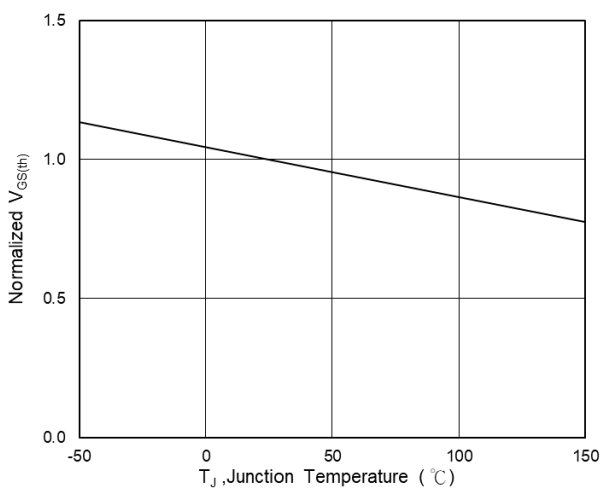


Fig.5 Normalized $V_{GS(th)}$ vs T_J

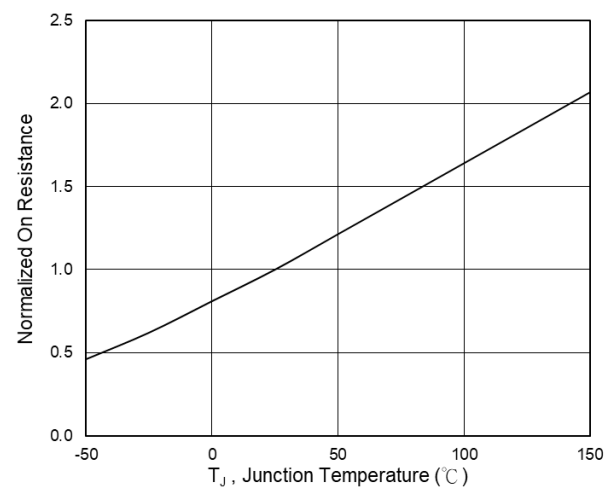


Fig.6 Normalized $R_{DS(on)}$ vs T_J

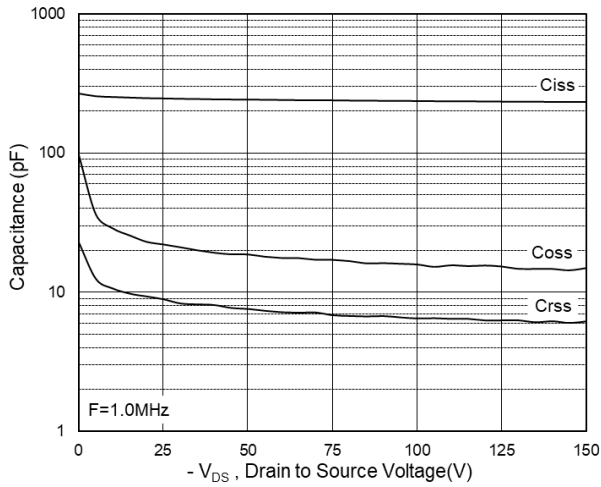


Fig.7 Capacitance

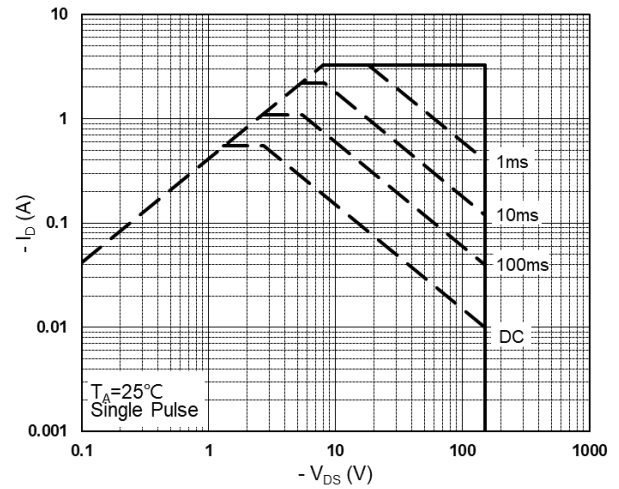


Fig.8 Safe Operating Area

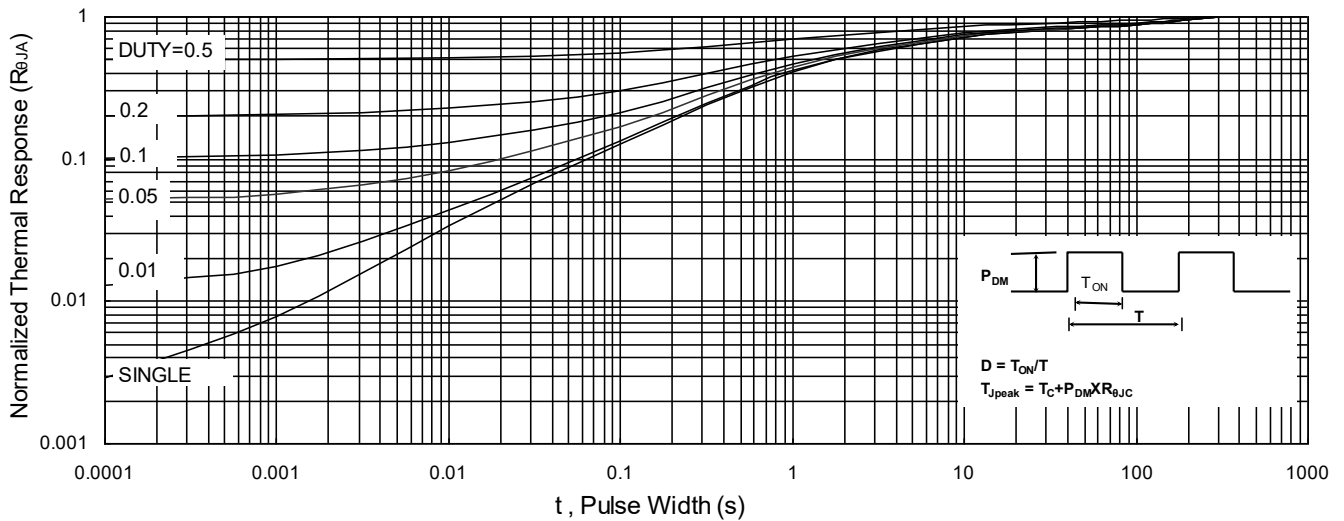


Fig.9 Normalized Maximum Transient Thermal Impedance

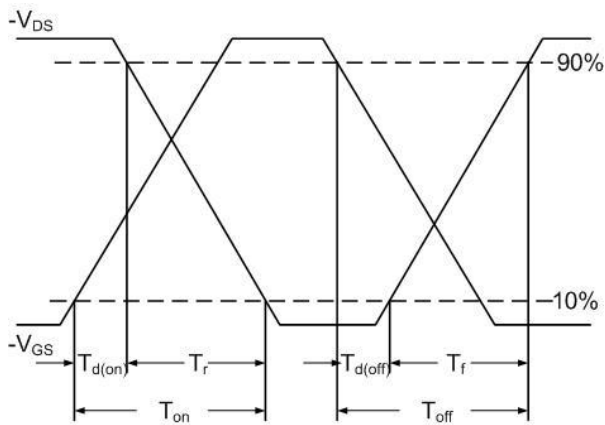


Fig.10 Switching Time Waveform

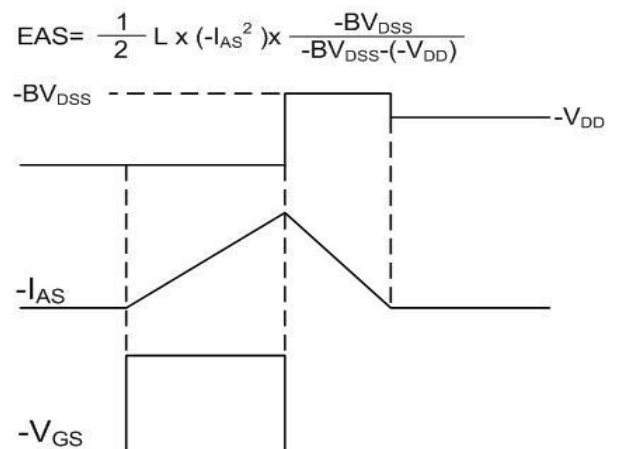
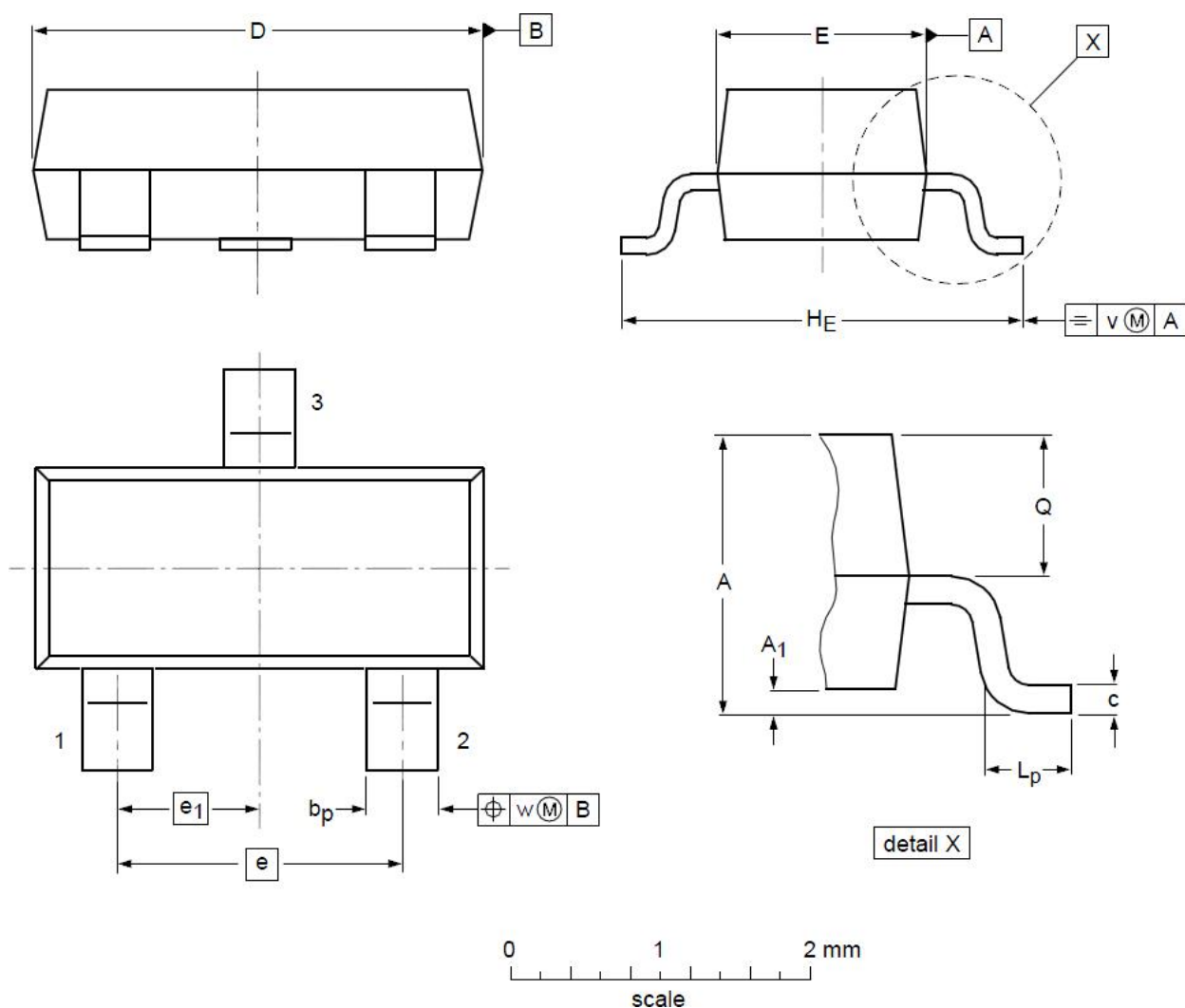


Fig.11 Unclamped Inductive Waveform

Package Mechanical Data-SOT-23



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A₁	0.01	0.05	0.10
b_p	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e₁	--	0.95	--
H_E	2.25	2.40	2.55	L_p	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				